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(54) ELECTRONIC EQUIPMENT

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(57) **ABSTRACT**

A heatsink (**21**) is disposed on a lower surface of a circuit board (**10**). The circuit board (**10**) has through holes (h**1**) that penetrate the circuit board (**10**) in an area (A) where an integrated circuit apparatus (**5**) is disposed. Heat conduction paths (**11**) are provided in the through holes (h**1**). The heat conduction paths (**11**) connect the integrated circuit apparatus **5** and the heatsink (**21**). This structure allows for disposition of a component different from the heatsink (**21**) on the same side as the integrated circuit apparatus (**5**), thus ensuring a higher degree of freedom in a component layout.